

SOT1342-1

plastic, extremely thin fine-pitch ball grid array package; 24 balls

8 June 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	XFBGA24
Package type industry code	XFBGA24
Package style descriptive code	XFBGA (extremely thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	25-9-2012

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.9	-	2	2.1	mm
E	package width	1.9	-	2	2.1	mm
A	seated height	-	-	-	0.5	mm
A ₂	package height	0.33	-	0.34	0.35	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	24	-	



2. Package outline

XFBGA24: plastic, extremely thin fine-pitch ball grid array package; 24 balls SOT1342-1

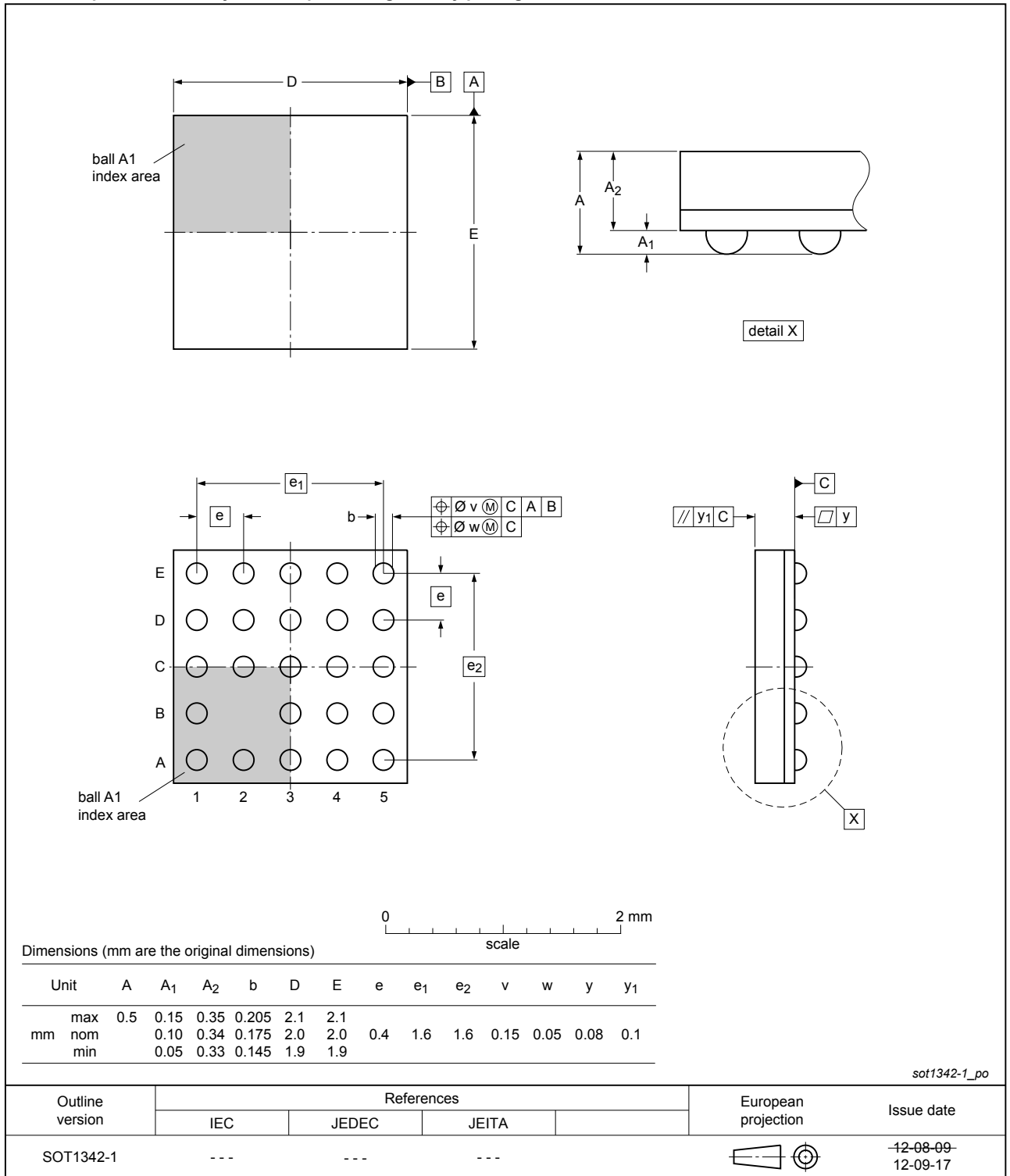
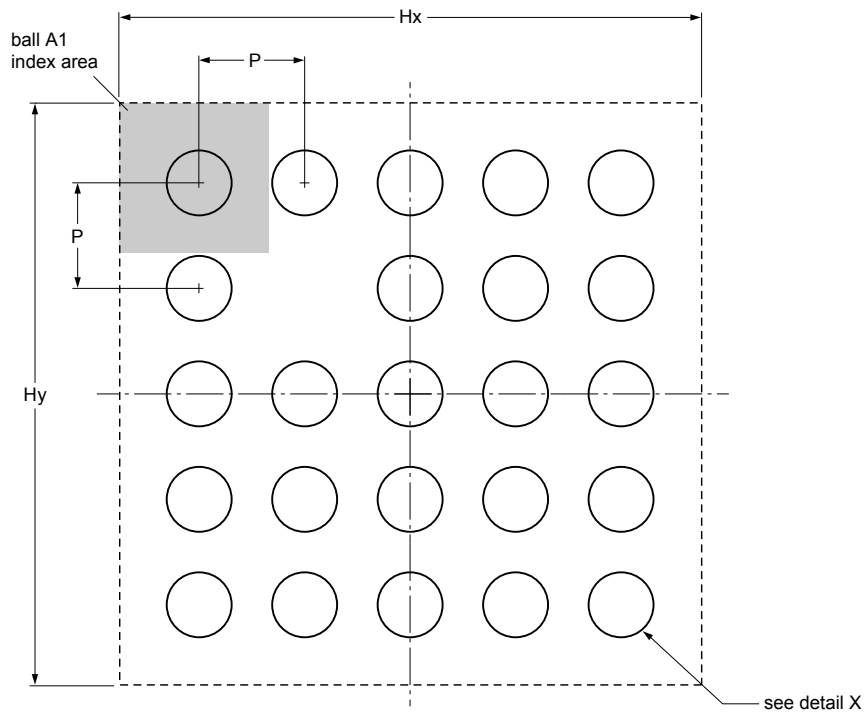


Fig. 1. Package outline XFBGA24 (SOT1342-1)

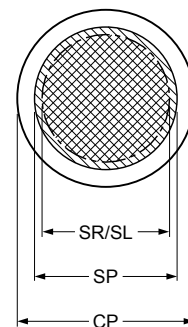
3. Soldering

Footprint information for reflow soldering of XFBGA24 package

SOT1342-1



- Cu pad (CP)
- solder land (SL)
- solder paste deposit (SP)
- solder land plus solder paste (SR)
- occupied area
- solder resist



detail X

Dimensions in mm

P	SR/SL	SP	CP	Hx	Hy
0.40	0.18	0.20	0.25	2.20	2.20

sot1342-1_fr

Fig. 2. Reflow soldering footprint for XFBGA24 (SOT1342-1)

4. Legal information

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